



## Material Content Data Sheet



Sales Product Name	TDA4863G			Issued		16. January 2020		
MA#	MA001039034							
Package	PG-DSO-8-41			Weight*		81.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.391	4.17	4.17	41743	41743
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		414	
	non noble metal	iron	7439-89-6	0.673	0.83		8286	
	non noble metal	copper	7440-50-8	27.330	33.64	34.52	336449	345253
wire	noble metal	gold	7440-57-5	0.091	0.11	0.11	1126	1126
encapsulation	organic material	carbon black	1333-86-4	0.142	0.17		1742	
	plastics	epoxy resin	-	4.575	5.63		56326	
	inorganic material	silicondioxide	60676-86-0	42.453	52.28	58.08	522614	580682
leadfinish	non noble metal	tin	7440-31-5	0.814	1.00	1.00	10019	10019
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1103	1103
glue	plastics	acrylic resin	-	0.326	0.40		4015	
	noble metal	silver	7440-22-4	1.305	1.61	2.01	16059	20074
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com